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(12) **United States Design Patent**
Ma et al.

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- (54) **BONE CONDUCTION HEADPHONES**
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- (**) Term: **15 Years**
- (21) Appl. No.: **29/848,620**
- (22) Filed: **Aug. 3, 2022**

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Primary Examiner — Paula Allen Greene

- (30) **Foreign Application Priority Data**
Mar. 24, 2022 (CN) 202230157900.2
- (51) **LOC (14) Cl.** **14-01**
- (52) **U.S. Cl.**
USPC **D14/205**
- (58) **Field of Classification Search**
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CPC H04R 25/00; H04R 25/02; H04R 1/1066;
H04R 1/1016; H04R 1/105; H04R
1/1033; H04R 5/033; H04R 5/0335;
H04R 1/1091
See application file for complete search history.

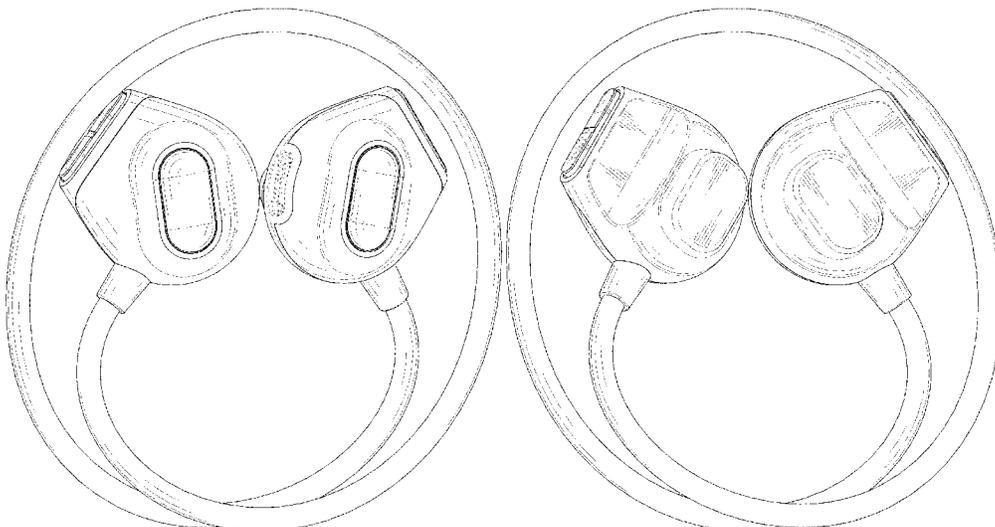
(57) **CLAIM**
The ornamental design for a bone conduction headphones, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of bone conduction headphones showing our new design;
FIG. 2 is another perspective view thereof;
FIG. 3 is a front elevational view thereof;
FIG. 4 is a rear elevational view thereof;
FIG. 5 is a left side elevational view thereof;
FIG. 6 is a right side elevational view thereof;
FIG. 7 is a top plan view thereof;
FIG. 8 is a bottom plan view thereof; and,
FIG. 9 is a perspective view of the bone conduction headphones where the bone conduction headphones is in a configuration of use.
The broken lines in the drawings depict portions of the bone conduction headphones that form no part of the claimed design.

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1 Claim, 9 Drawing Sheets



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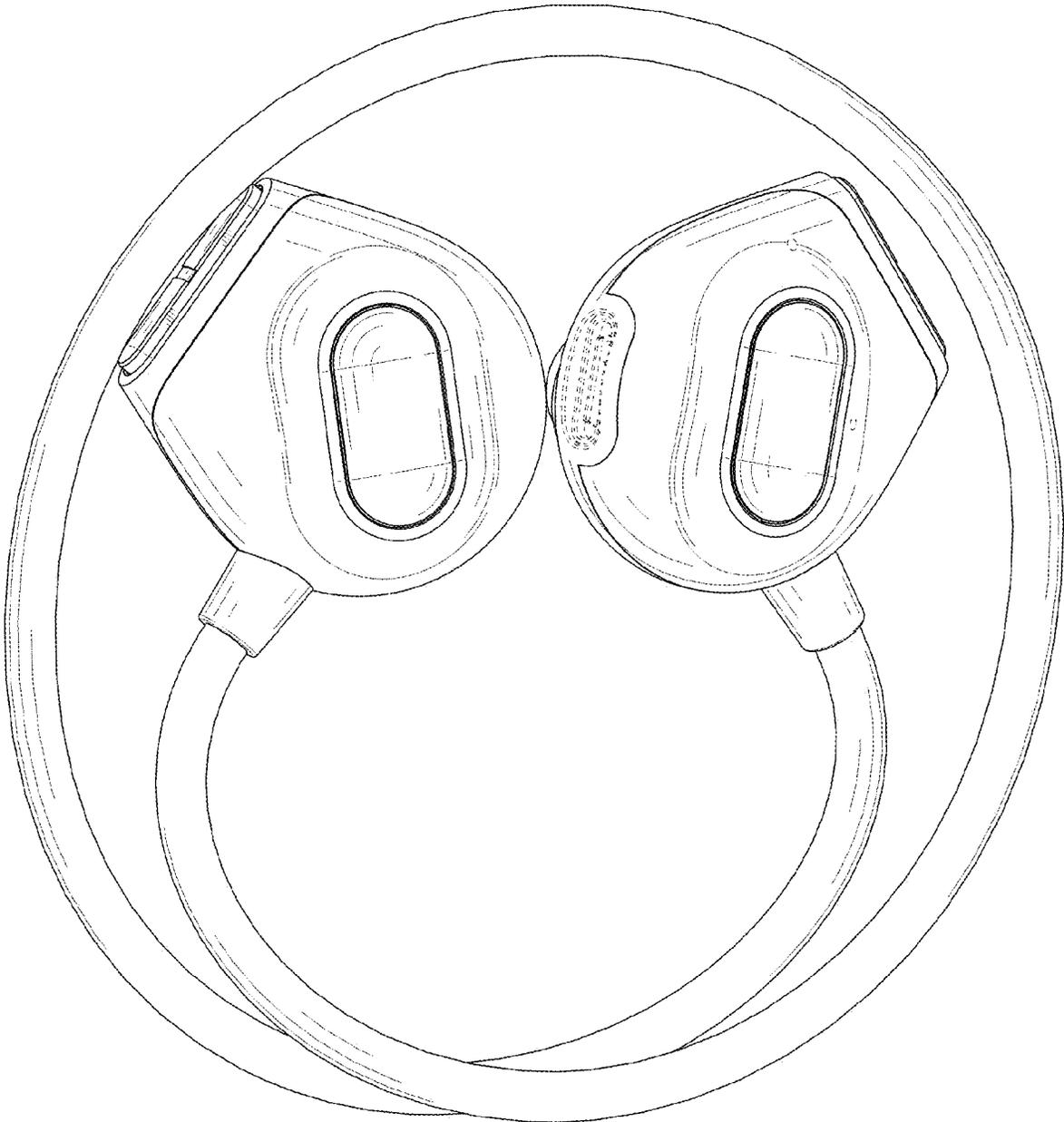


FIG. 1

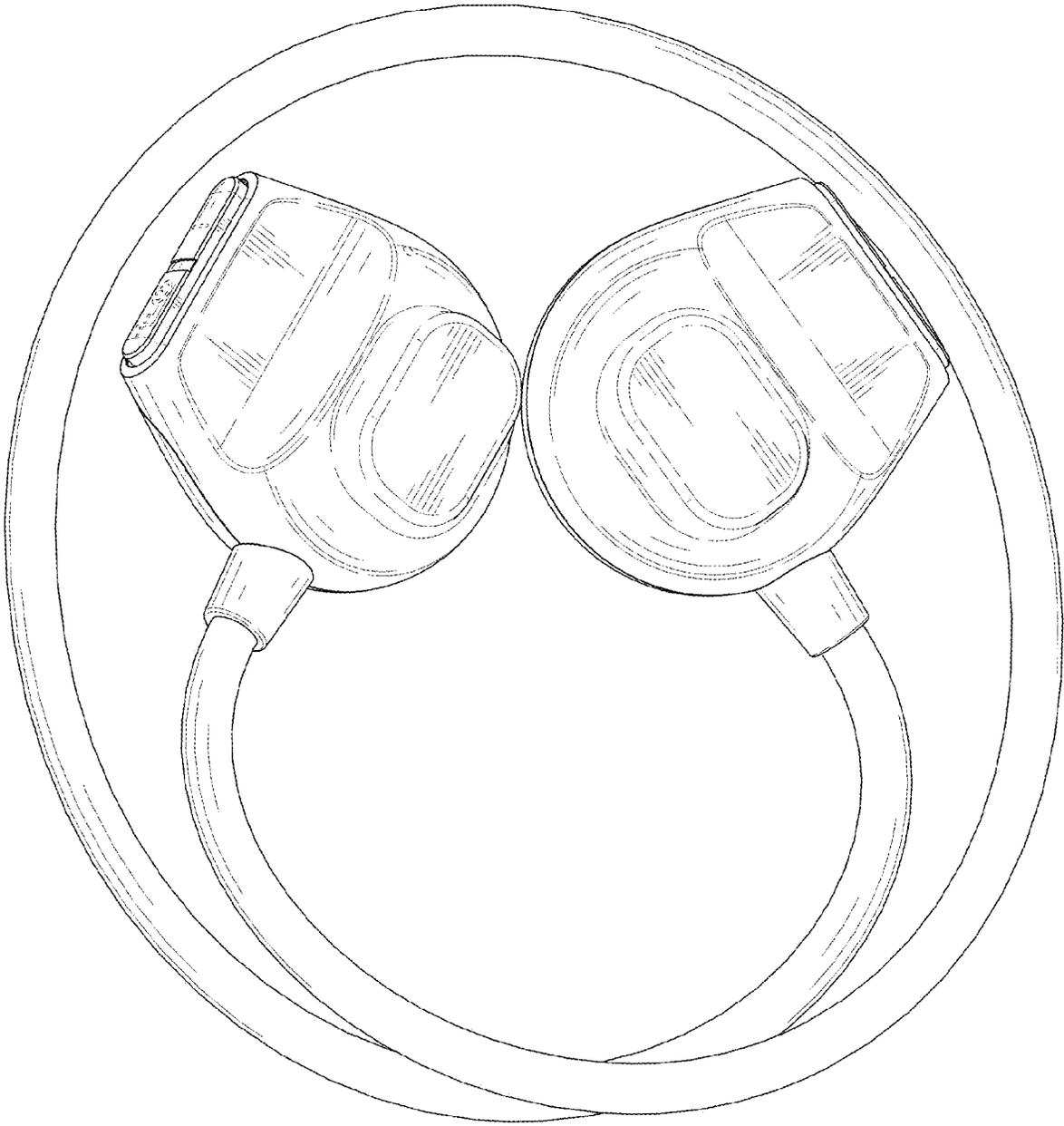


FIG. 2

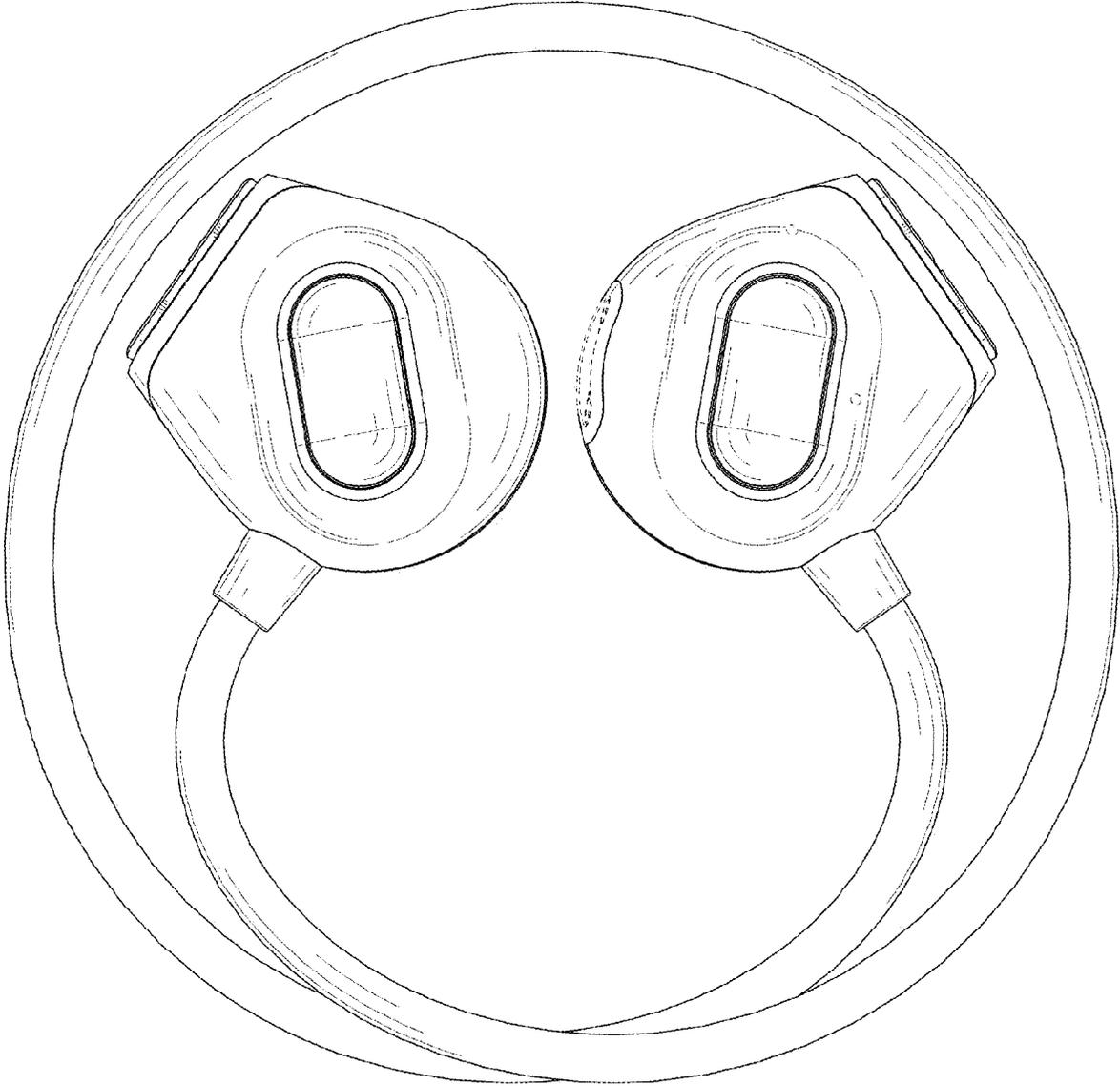


FIG. 3

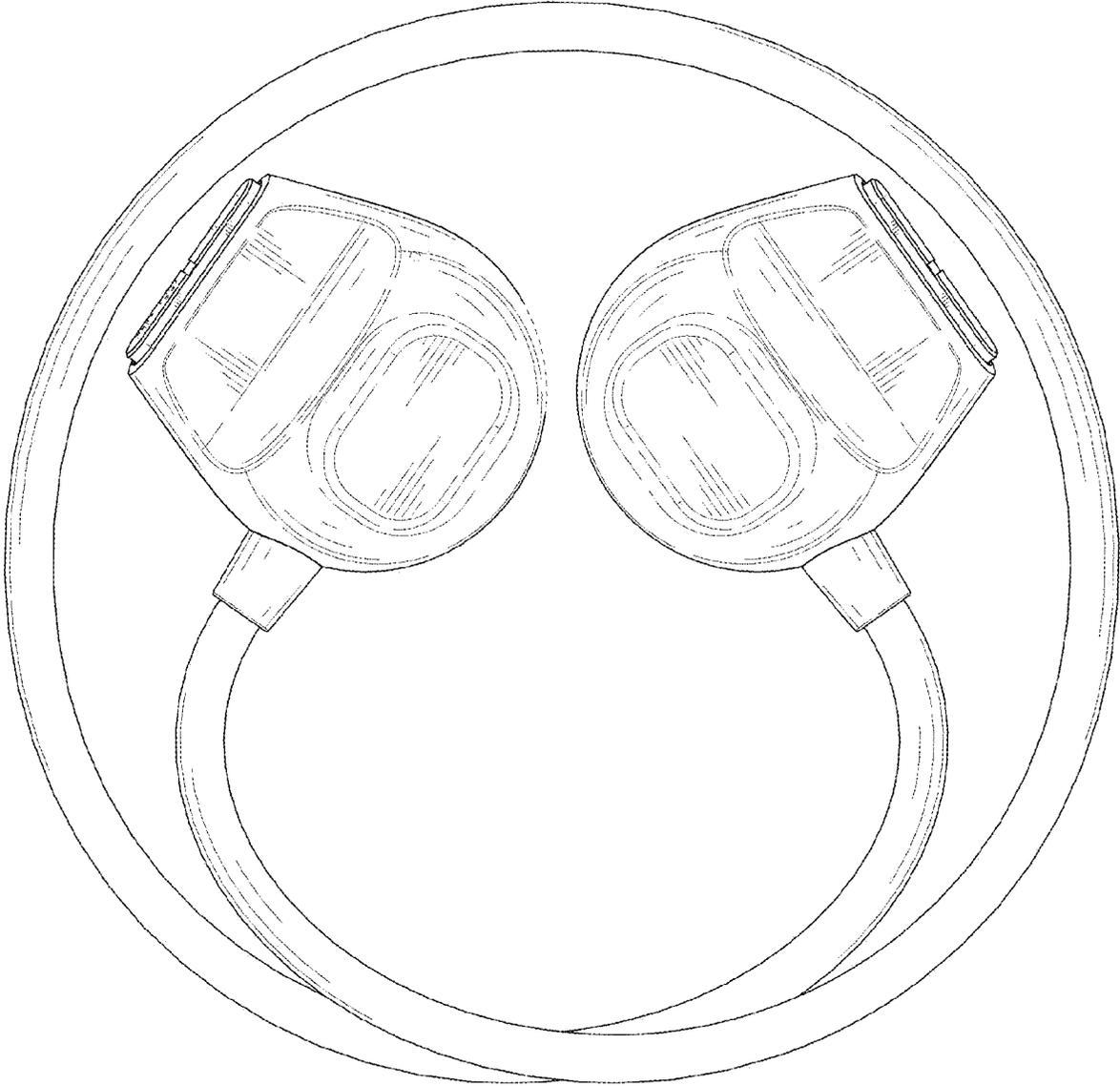


FIG. 4

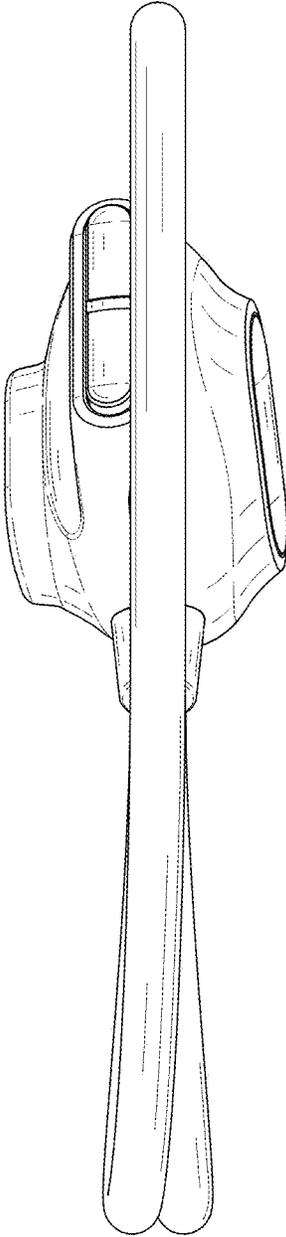


FIG. 5

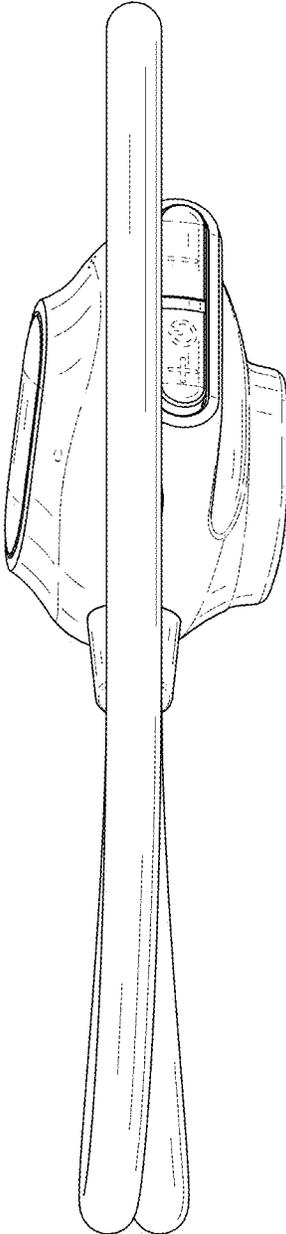


FIG. 6

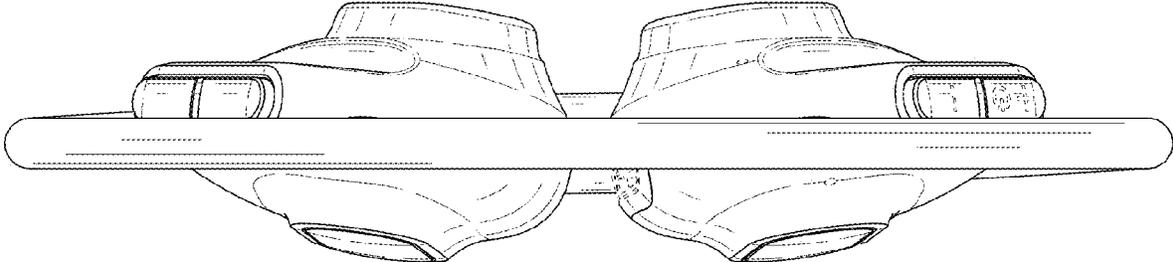


FIG. 7

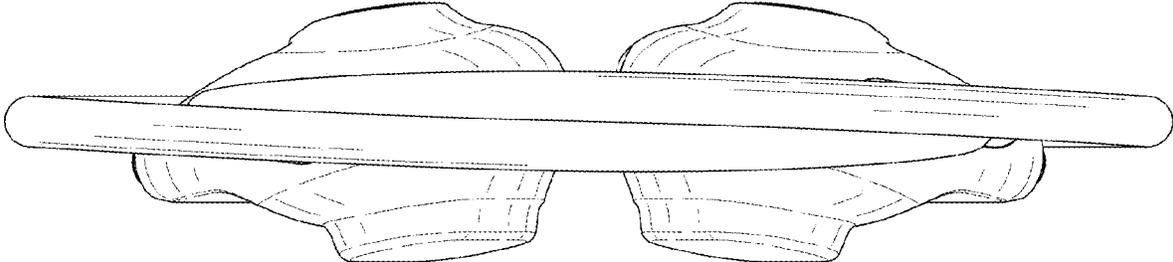


FIG. 8

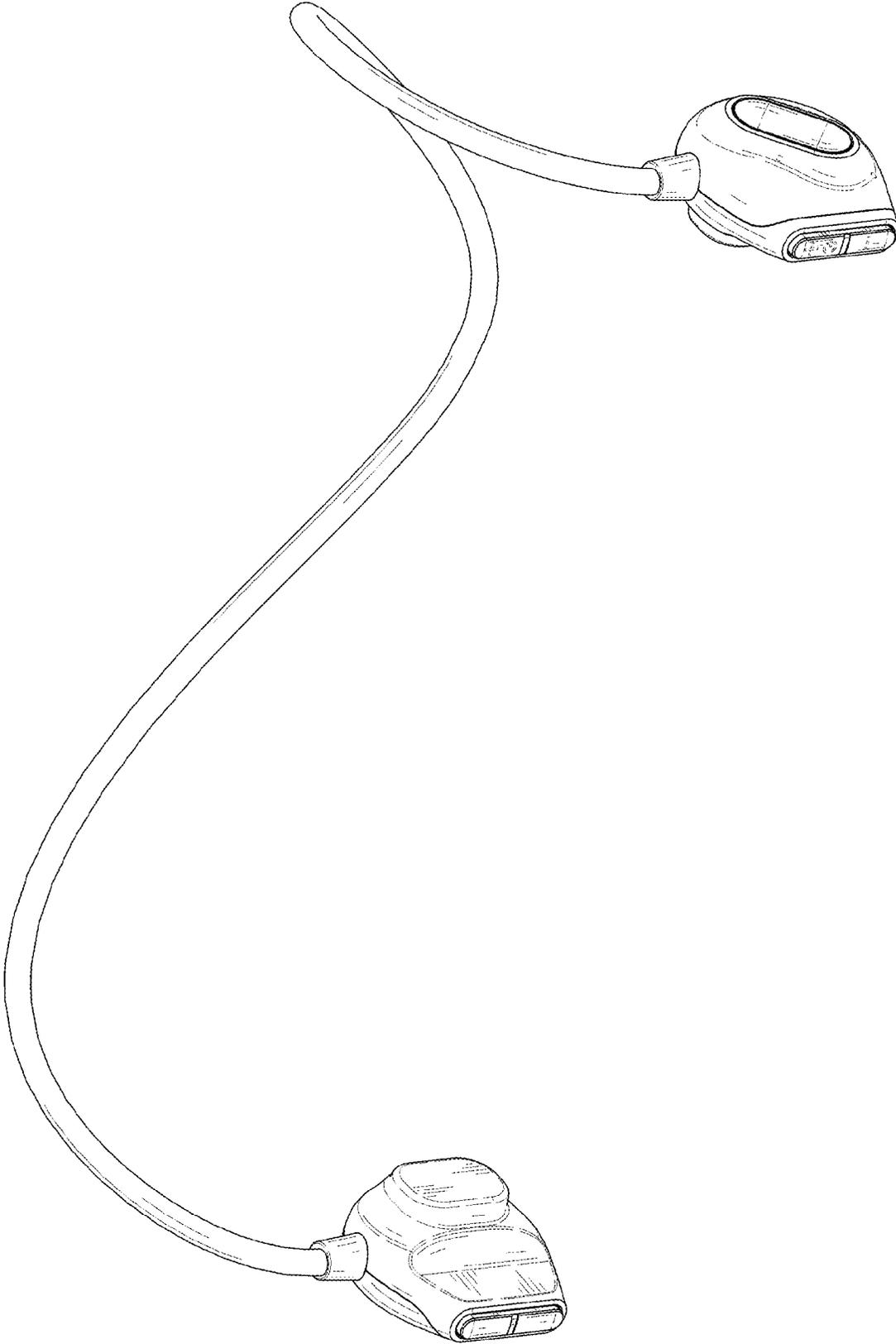


FIG. 9